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31 August – 2 September 2022

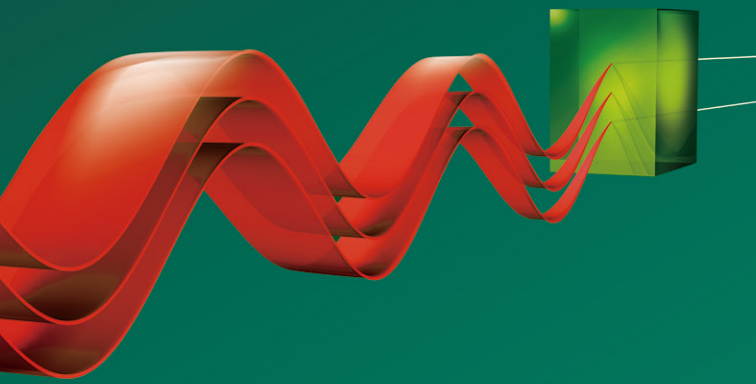
Shanghai New International Expo Centre (SNIEC), China

International Exhibition and Conference for Power Electronics, Intelligent Motion, Renewable Energy and Energy Management

Call for Papers

Highlighted Topic in 2022: Electrification of Transportation Systems

www.pcimasia-expo.com



Proceedings Publisher

IET Inspec Direct | IEEE Xplore | Scopus

Become a Speaker

You are forward-thinking expert in the field of power electronics and would like to inspire an audience of around 500 conference attendees with your latest developments and research findings?

Join us at PCIM Asia Conference and inspire others with your ideas!

Why be a speaker?

- Publication of your paper in the PCIM Asia Conference proceedings, IET Inspec-Direct, IEEExplore and Scopus

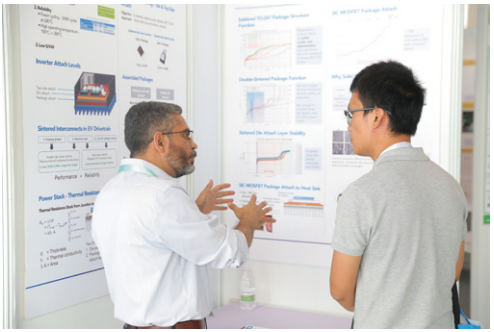
IET Inspec Direct IEEE Xplore Scopus

- Exchange experiences with power electronics experts and expand your knowledge on current and upcoming industry trends.
- Establish new contacts and take advantage of networking opportunities with global leading industry brands.

Submission requirements available at
www.pcimasia-expo.com

Dates to remember

- Submission of abstracts before **1 March 2022**
- Notification of acceptance on **May 2022**
- Submission of full paper before **20 June 2022**



Chance to win the awards

The papers for the awards will be selected upon the paper submissions by the Advisory Board and Technical Committee, and will be granted at PCIM Asia 2022 Conference. The winners will receive prize money of RMB 8,000 each.

pcim Asia
Best Paper Award

pcim Asia
Young Engineer Award

All details at
www.pcimasia-expo.com

Topics of Interest

★ **Highlighted Topic in 2022: Electrification of Transportation Systems**

1. Advanced Power Semiconductors
1.1 High Power Semiconductors
1.2 MOSFETs, IGBTs, FREDs & Schottkys
1.3 Power Modules and Power Hybrids
1.4 SiC, GaN and other Wide Bandgap Devices and their Applications
1.5 Power Supply Control IC and Power Management ICs
1.6 Gate Driver and Device Protection
1.7 IPM and Power Electronic Building Blocks

2. Packaging and Reliability
2.1 Packaging and Interface Technologies
2.2 Advanced Cooling Systems
2.3 Thermal Modelling and Simulations
2.4 Power Electronic Components Reliability
2.5 Power Embedding
2.6 High Power Density Designs

3. Passive Components and Integration
3.1 Higher Frequency and Low Loss Materials & Techniques for Inductors and Capacitors
3.2 Planar Inductors and Transformers and Thin Film Magnetic Component
3.3 Filters and Passive Integration

4. AC/DC Converter
4.1 High Efficiency/High Density Power Converters/Inverters
4.2 Resonant and Quasi Resonant Topologies for Power Supplies
4.3 Stand-alone Power Supplies (Adapters) and on Board Supplies
4.4 New Topologies (Single Switch, Phase Shift, ZVS, ZCS, ZVZCS)

5. DC/DC Converter
5.1 DC/DC Converter Topologies for Enhanced Efficiency and Control
5.2 Synchronous Rectification
5.3 Smart Battery Management Concepts
5.4 Point of Load Converters
5.5 New Topologies for Distributed Power Supply Systems (Single or Multi-Stage Architecture, ZVS, ZCS, ZVZCS)

6. Digital Power Conversion
6.1 PMBus and other Digital Power Control Protocols
6.2 Digital Control for Power Converters
6.3 Advantages of Digital Power Conversion and Associated Challenges
6.4 System on a Chip (SOC)
6.5 Energy Harvesting

7. Motor Drive & Motion Control
7.1 Home Appliances
7.2 Small Power Motor "General Purpose Drive" with Highly Sophisticated Control Strategies and Low Cost Solutions
7.3 New Converter/Inverter Types for Single- and Three Phase Systems
7.4 Advanced Motor Concepts for Industrial Application and Traction Drives
7.5 New Control Architectures DSP, Microcontroller or FPGA
7.6 Advanced Sensor Concepts for Motor Drives
7.7 Intelligent Motion Control and Architecture

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8. High Frequency Power Electronic Converters and Inverters

8.1 Thermal Design, Packaging and EMI Issues
8.2 Sensors Specific to Power Electronics (e.g. voltage, current, power, frequency, phase, temperature)
8.3 Techniques to Reduce Switching Losses to Improve Efficiency and Reduce Size and Weight
8.4 Wireless Power Transfer

9. Automotive Power Electronics

9.1 Hybrid-/ Electric Vehicle
9.2 MOSFET and IGBT Modules in Motor Traction Applications
9.3 DC/DC Conversion in Automobiles
9.4 Bidirectional DC/DC Converters
9.5 Electronics for Powertrain and Power Management
9.6 Energy Storage and Management, including Battery Types, Super Capacitors and Fly Wheels
9.7 DC Circuit Breaker

10. System Reliability

10.1 Reliability and Health Management of Power Electronic Components and Systems
10.2 Fail-safe and Fault-tolerant Applications
10.3 Redundancy Concepts in Power Electronics
10.4 Life Cycle Cost Analysis

11. Power Quality Solutions

11.1 UPS Systems and Inverters
11.2 Active Power Filter (APF), DVR, SVG
11.3 Energy Storage System (Battery Technologies, Flywheel, Super (ultra) Capacitors)
11.4 Harmonics and Power Factor Correction

12. Smart Grid Power Electronics

12.1 Grid Inverter Control
12.2 Battery Charging and V2G
12.3 Energy Storage System and Control
12.4 Micro-Grid
12.5 Solid State Transformers
12.6 Medium Voltage Multilevel Converters
12.7 Modular Multilevel Converters
12.8 Novel Converter Topologies
12.9 Wind Energy Systems
12.10 Solar and Photovoltaic Energy Systems

13. Power Electronics in Transmission Systems

13.1 FACTS
13.2 Converters for Offshore/Onshore HVDC Links
13.3 Power Generation, Transmission and Distribution
13.4 DC Grids
13.5 HVDC Systems

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» Being able to identify the industry's development trends, this makes the PCIM Asia Conference platform even more important for industry players to focus on developing the right products and technologies to meet the demands of the future.«
Leo Lorenz, ECPE, Germany

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Leo Lorenz, ECPE, DE

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* No specific order

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